

J/4/1

DIALOG(R) File 351:Derwent WPI

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IM- *Image available*

AA- 2000-266791/200023 |

XR- <XRAM> C00-081680|

TI- Adhesion member, comprises surface layer of specific thickness on adhesion layer, which is provided on side(s) of base material and the adhesion characteristics of the surface layer and adhesion layer are different|

PA- NITTO DENKO CORP (NITL)|

NC- 001|

NP- 001|

PN- JP 2000073029 A 20000307 JP 98257545 A 19980826 200023 B|

AN- <LOCAL> JP 98257545 A 19980826|

AN- <PR> JP 98257545 A 19980826|

FD- JP 2000073029 A C09J-007/02|

LA- JP 2000073029(8)|

AB- <BASIC> JP 2000073029 A

NOVELTY - An adhesion layer (1) is provided on side(s) of base material (2). A surface layer (11) of thickness 50 nm or less is provided on the adhesion layer. The adhesion characteristics of the surface layer is different from the adhesion layer.

DETAILED DESCRIPTION - An INDEPENDENT CLAIM is also included for the manufacture of adhesion member. The adhesion layer on the base material is configured at remote plasma area, the surface layer is modified.

USE - The adhesion member is useful as label, seal, sticker, emblem, voucher, notice plate, packaging tape, surface protection material and adhesion sheet.

ADVANTAGE - The surface layer is modified easily and the bulk characteristics of the adhesion layer is maintained. The adhesion member excels in flexibility, surface protection property, re-peelability, retention strength and adhesive strength.

DESCRIPTION OF DRAWING - The figure shows the sectional drawing of adhesion member. (1) Adhesion layer; (2) Base material; (11) Surface layer.

Dwg.1/3|

DE- <TITLE TERMS> ADHESIVE; MEMBER; COMPRISE; SURFACE; LAYER; SPECIFIC; THICK; ADHESIVE; LAYER; SIDE; BASE; MATERIAL; ADHESIVE; CHARACTERISTIC; SURFACE; LAYER; ADHESIVE; LAYER|

DC- A81; G03|

IC- <MAIN> C09J-007/02|

IC- <ADDITIONAL> C09J-123/22; C09J-133/08|

MC- <CPI> A12-A01A; G03-B04|

FS- CPI||

?s pn=jp 11277699

S4

1 PN=JP 11277699

?t s4/4/all

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AA- 2000-016589/200002 |

XR- <XRAM> C00-003759|

XR- <XRPX> N00-013094|

TI- Metal layer laminated polyimide film for electronic components - has plasma treated polyimide film laminated to metal layers either directly or using heat-resistant adhesive|

PA- UBE IND LTD (UBEI)|

NC- 001|

NP- 001|

PN- JP 11277699 A 19991012 JP 9885510 A 19980331 200002 B|

AN- <LOCAL> JP 9885510 A 19980331|

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